

### Amendments to the Specification

Kindly amend the application as follows.

Replace the paragraph beginning at page 9, line 26, with the following rewritten paragraph.

~~--Figure 1 depicts~~ Figures 1A-1F depict an exemplary contact stamping method according to the invention;

Figure 2 depicts a balloon-like stamp configured to pattern a substrate;

Figure 3 depicts an exemplary method of fabricating a stamp according to the invention;

Figure 4 depicts an exemplary stamping apparatus for use with a stamp according to the invention;

~~Figure 5 depicts~~ Figures 5A-5D depict an exemplary method of stamping the interior of a substrate;

Figure 6 depicts an exemplary method for re-inking a stamp;

Figure 7 depicts an exemplary method for re-inking a stamp;

~~Figure 8 depicts~~ Figures 8A-8D depict the motion of a roller and a substrate for rolling microcontact printing;

Figure 9 depicts an exemplary fluidic patterning method according to the invention; and

Figure 10 is a cross-sectional view of lithographic masks fabricated according to an embodiment of the invention.--

Replace the paragraph beginning at page 3, line 27, with the following rewritten paragraph.

--In one aspect, the invention is a method of stamping a surface. The method comprises providing a stamp having a stamping surface, disposing a substrate proximate to the stamping surface, and modulating the dimensions of the stamp to place the stamping surface in contact with substrate. The method may further comprise modulating the dimensions of the stamp before the step of disposing the substrate. The method may further comprise modulating the dimensions of the stamp to facilitate removal of the stamping surface ~~of~~ from the substrate. Modulating the dimensions may comprise applying a mechanical stress or an electrical stimulus, removing a mechanical stress or an electrical stimulus, creating or venting a vacuum, applying or removing a magnetic field, or any combination of the above. The mechanical stress may

comprise a positive or negative hoop stress, a tensile stress, or a hydrostatic stress. The entirety of the stamp may be modulated at the same time. At least one of the stamping surface and a surface of the substrate may exhibit convexity in at least one dimension not resulting from a surface texture or pattern. The method may further comprise exposing the substrate to electromagnetic radiation by transmitting said radiation through the stamp, portions of which may be opaque. The stamping surface may comprise a pattern comprising at least one channel defined by raised portions on the surface of the stamp. A lateral dimension of a channel or raised portion may be 100 nm or greater.—

Replace the paragraph beginning at page 27, line 18, with the following rewritten paragraph.

--A variety of materials with flowable precursors may also be patterned on a substrate via fluidic techniques. Polymers may be patterned on the substrate by flowing a liquid pre-polymer or monomer through the channels and exposing it to ultraviolet light through a transparent stamp. Self-curing polymers such as epoxies may also be patterned on the surface. In another embodiment, the fluid passed across the substrate may be exposed to an electric or magnetic field or heated. For example, a heated fluid may be passed through the network of voids, and it is also possible to heat the fluid directly as it passes over the substrate. For example, a metallic substrate may also serve as a heater through resistive heating, or the entire apparatus may be heated, for example, in an oven or radiatively. Sol-gel techniques may be exploited to form ceramics and other materials with the channels in the stamp serving as a mold for the sol. Colloids, inorganic materials, hybrid organic/inorganic materials, and biological materials can also be molded on the surface. The material is dissolved or suspended in a solvent and passed into the network of voids, following which the solvent is allowed to dissipate, leaving the molded material behind. The material may be cross-linked or crystallized as the solvent is dissipated. Other techniques for hardening flowable material in capillaries may also be exploited for use with the stamps of the invention. Exemplary techniques are described in U.S. Patent No. 6,044,444 ~~6,004,444~~ and Xia, *et al.*, "Soft Lithography," *Angew. Chem. Int. Ed.*, **37**:550-575 (1998), the entire contents of both of which are incorporated herein by reference.